FAIRCHILD

SEMICONDUCTOR TM

FQNL1N50B **500V N-Channel MOSFET**

General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply, power factor correction, electronic lamp ballast based on half bridge.

Features

- 0.27A, 500V, $R_{DS(on)}$ = 9.00 @V_{GS} = 10 V Low gate charge (typical 4.0 nC)
- Low Crss (typical 3.0 pF)
- Fast switching
- Improved dv/dt capability



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQNL1N50B	Units
V _{DSS}	Drain-Source Voltage		500	V
I _D	Drain Current - Continuous ($T_C = 25^{\circ}C$) - Continuous ($T_C = 100^{\circ}C$)		0.27	A
			0.17	А
I _{DM}	Drain Current - Pulsed	(Note 1)	1.08	А
V _{GSS}	Gate-Source Voltage		± 30	V
I _{AR}	Avalanche Current	(Note 1)	0.27	А
E _{AR}	Repetitive Avalanche Energy	(Note 1)	0.15	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 2)		4.5	V/ns
P _D	Power Dissipation ($T_C = 25^{\circ}C$)		1.5	W
	- Derate above 25°C		0.012	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
R_{\thetaJA}	Thermal Resistance, Junction-to-Ambient		83	°C/W

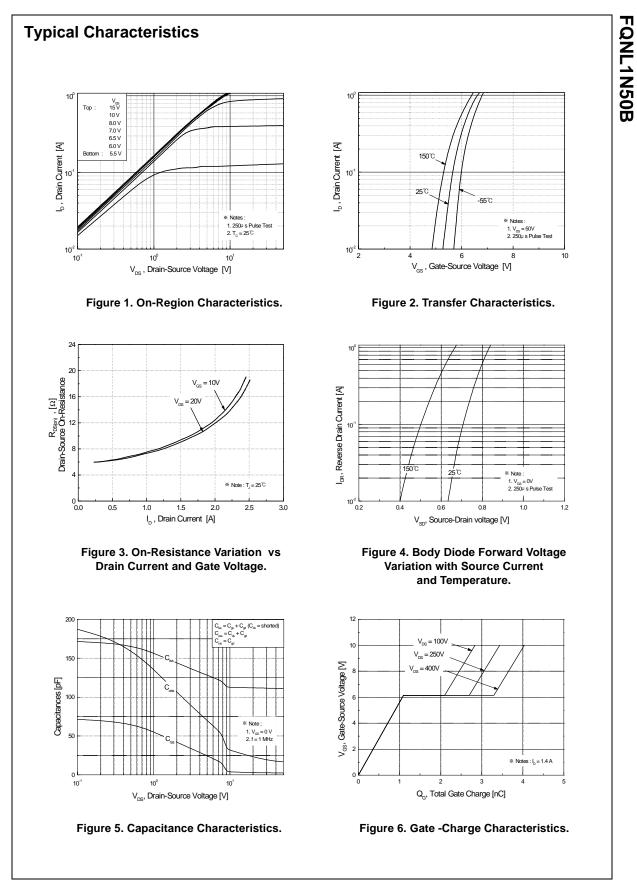
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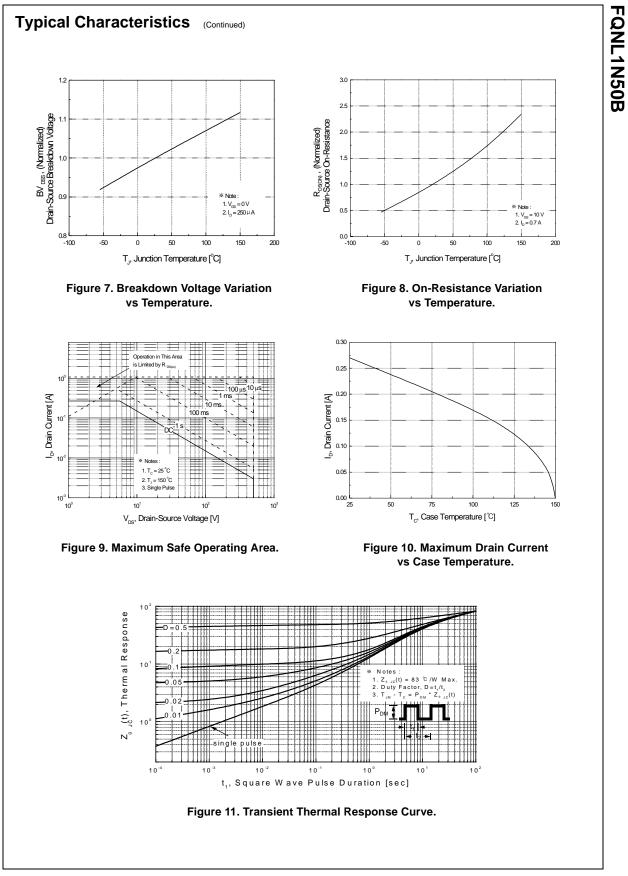
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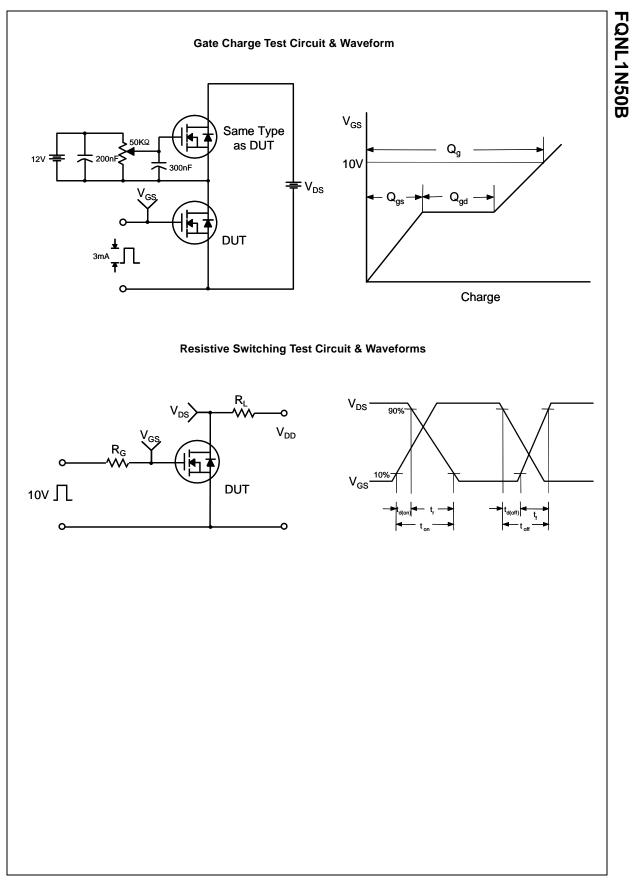
FQNL1N50B

)ff Chai	Parameter	Test Conditions	Min	Тур	Max	Units
	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	500			V
ABV _{DSS}	Breakdown Voltage Temperature		500			v
ΔT_{J}	Coefficient	$I_D = 250 \ \mu A$, Referenced to $25^{\circ}C$		0.5		V/°C
DSS	Zaro Cato Voltago Drain Current	$V_{DS} = 500 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μA
	Zero Gate Voltage Drain Current	V _{DS} = 400 V, T _C = 125°C			10	μA
GSSF	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$			100	nA
GSSR	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$			-100	nA
On Char	racteristics					
/ _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.3	3.0	3.7	V
GS(th)	Cale micshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \text{ mA}$	3.6	4.3	5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =0.135 A		6.8	9.0	Ω
FS	Forward Transconductance	V _{DS} = 50 V, I _D = 0.135 A (Note 3)		0.55		S
		· · ·	1		I.	1
-	c Characteristics		1		450	_
Siss	Input Capacitance	$V_{DS} = 25 V, V_{GS} = 0 V,$		115	150	pF
Coss	Output Capacitance	f = 1.0 MHz		20	30	pF
2 _{rss}	Reverse Transfer Capacitance			3.0	4.0	pF
	ng Characteristics		1	-		
d(on)	Turn-On Delay Time	V _{DD} = 250 V, I _D = 1.4 A,		5	20	ns
r	Turn-On Rise Time	$R_{G} = 25 \Omega$		25	60	ns
d(off)	Turn-Off Delay Time			8	25	ns
f	Turn-Off Fall Time	(Note 3, 4)		20	50	ns
ζ _g	Total Gate Charge	$V_{DS} = 400 \text{ V}, \text{ I}_{D} = 1.4 \text{ A},$		4.0	5.5	nC
λ _{gs}	Gate-Source Charge	V _{GS} = 10 V		1.1		nC
2 _{gd}	Gate-Drain Charge	(Note 3, 4)		2.2		nC
Drain-So	ource Diode Characteristics ar	nd Maximum Ratings				
s	Maximum Continuous Drain-Source Dic	-			0.27	Α
SM	Maximum Pulsed Drain-Source Diode F	Forward Current			1.08	А
	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 0.27 A			1.4	V
/ _{SD}	Reverse Recovery Time	$V_{GS} = 0 V, I_{S} = 1.4 A,$		170		ns
/ _{SD} rr	Reverse Recovery Time	$V_{GS} = 0, V_{S} = 1.4, V_{S}$				
	Reverse Recovery Charge	$dI_{\rm F} / dt = 100 \text{ A/us}$ (Note 3)		0.4		μC

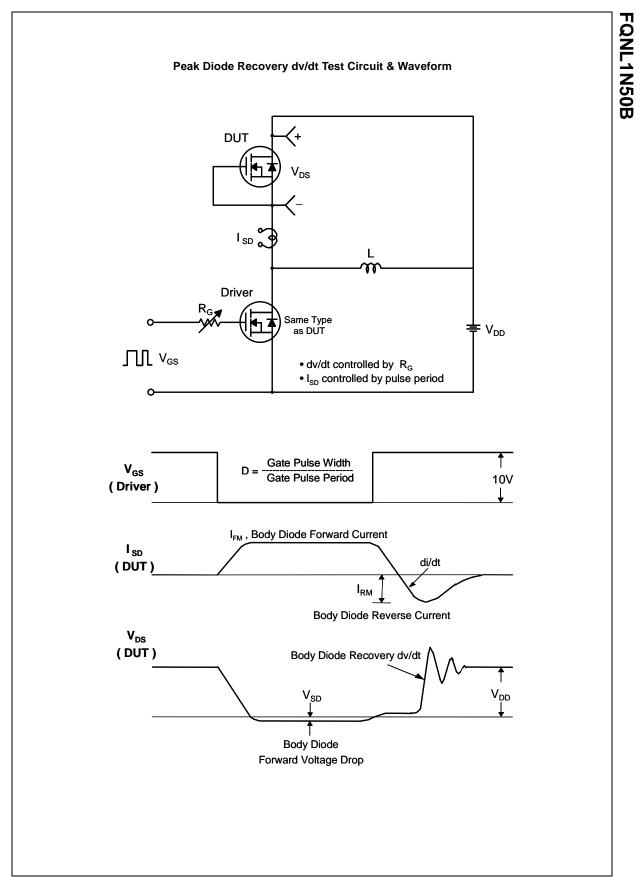
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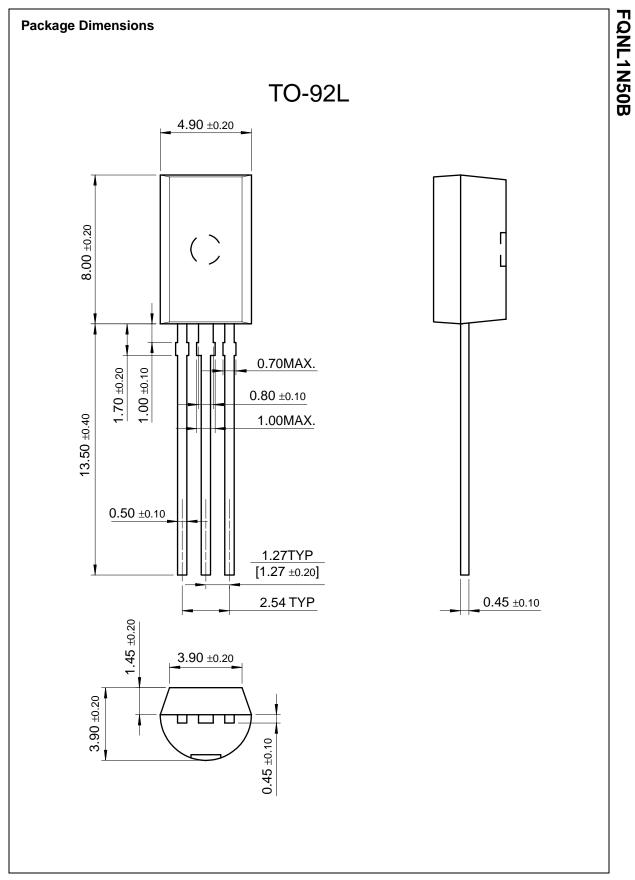




Rev. A, March 2001



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